

Cypress Semiconductor Qualification Report

QTP# 91512, Version 1.0
September, 1998

28-pin, 300-mil PDIP Package
Omedata, Indonesia Assembly

CYPRESS TECHNICAL CONTACT FOR QUALIFICATION DATA:

Marc Hartranft
Reliability Manager

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PLASTIC PACKAGE/ASSEMBLY DESCRIPTION			
Package Outline, Type, or Name:	28-pin, 300-mil PDIP		
Mold Compound Name/Manufacturer:	Sumitomo EME-6300H		
Lead Frame material:	Copper		
Lead Finish, composition:	Solder Plated, 85%Sn, 15%Pb		
Die Attach Area Plating:	Silver		
Die Attach Method:	Epoxy	Die Attach Material:	Silver Epoxy
Wire Bond Method:	Thermosonic	Wire Material/Size:	Gold / 1.3 mil
JESD22-A112 Moisture Sensitivity Level	N/A		
Assembly Line ID and Process ID:	Omedata, Indonesia (IDNS-0)		

Note: Please contact a Cypress Representative for other packages availability.

RELIABILITY TESTS PERFORMED

Stress/Test	Test Condition (Temp/Bias)	Result P/F
Temperature Cycle	JEDEC 22 A104, Condition B, -40°C to 125°C	P
High Accelerated Saturation Test	130°C/5.5V	P
High Temperature Storage	185°C, no bias	P
Pressure Cooker Test	121°C,100%RH	P

RELIABILITY TEST DATA

QTP#: 91512

DEVICE	ASSY-LOC	FABLOT#	ASSYLOT#	DURATION	S/S	REJ	FAIL MODE
STRESS: HI-ACCEL SATURATION TEST (130C, 85%RH, 5.5V)							
CY7C199-PC	INDNS-O	2131822	72568	100	50	0	
CY7C199-PC	INDNS-O	2120364	72910	100	45	0	
STRESS: HIGH TEMPERATURE STORAGE (185C, NO BIAS)							
CY7C199-PC	INDNS-O	2120364	72910	336	15	0	
CY7C199-PC	INDNS-O	2120364	72910	1000	15	0	
STRESS: PRESSURE COOKER TEST (121C, 100%RH)							
CY7C199-PC	INDNS-O	2131822	72568	168	50	0	
CY7C199-PC	INDNS-O	2120364	72910	168	45	0	
STRESS: TC JEDEC22 A104, CONDITION. B, -40 TO 125C							
CY7C199-PC	INDNS-O	2131822	72568	300	50	0	
CY7C199-PC	INDNS-O	2131822	72568	1000	50	0	
CY7C199-PC	INDNS-O	2120364	72910	300	45	0	
CY7C199-PC	INDNS-O	2120364	72910	1000	44	0	